



# eSIM

**Future-proof SIM with ability  
to support any mobile operator.**

Developed by the GSMA, and already widely accepted by the telecoms market, eSIM is the new standard in SIM technology. It simplifies the process of installing an operator's connectivity credentials, known as an eSIM profile, on to a device by using a standardised, secure and remote 'over the air' process. This eSIM brings wide ranging benefits to consumers, enterprises and IoT solutions.

**TRUPHONE**

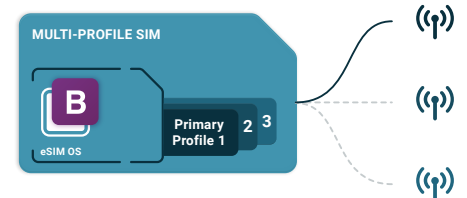


## Interoperable

The Truphone Io3 eSIM implements the GSMA eSIM specifications and is interoperable with any GSMA-compliant remote SIM provisioning platform, including but not limited to Truphone's own GSMA-accredited remote SIM provisioning platform. This means that for Consumer and M2M devices the eSIM can securely provision and store multiple operator profiles in a single integrated chip.

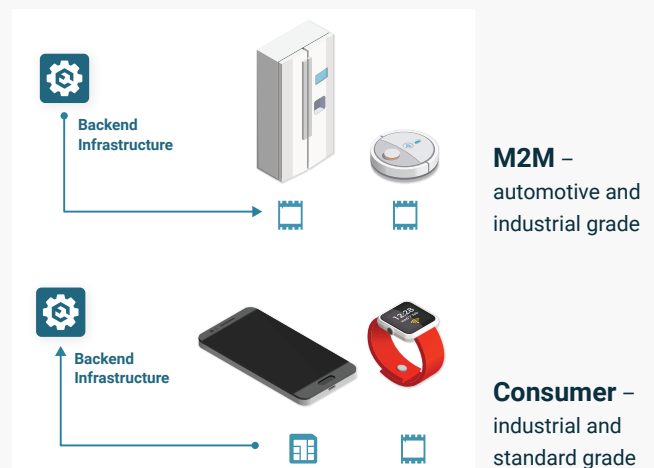
### With eSIM it's possible to:

- ✓ **Load operator profiles** to multiple devices remotely, over the mobile network or using Wi-Fi.
- ✓ **Swap profiles** without removing the SIM. Store multiple profiles on a single device.
- ✓ **Connect any device more efficiently.** Due to the flexibility of SIM form factors which often take up much less tech real estate than traditional SIMs.
- ✓ **Allow roaming and moving devices** to automatically navigate between network providers.
- ✓ **Enable IoT deployments** to get updated by pushing profile changes to the devices from a unified control platform



## Form factors

eSIM technology (also known as an eUICC) does not actually always need to be 'embedded'. Truphone can also provide eSIM modules in several different form factors—from the 'traditional' forms including mini (2FF), micro (3FF) and nano (4FF) as well as separate embedded chips such as MFF2. These modules come in the following grades depending on the required use case:



## Specifications

- ✓ Available in Consumer and M2M configurations to support any IoT or consumer device
- ✓ Can provide eSIM hardware modules in 2FF, 3FF, 4FF, MFF2 and WLCSP form factors.
- ✓ Support different form factors of mini (2FF), micro (3FF) and nano (4FF), MFF2 and WLCSP
- ✓ Can come preloaded with Truphone Bootstrap
- ✓ Support for any certified Remote SIM provisioning platform that supports GSMA SGP .22 (V2.2) or GSMA SGP .02 (V3.1)
- ✓ GSMA-compliant eUICC
- ✓ Global Platform qualified for eUICC M2M V3.1 and Consumer SGP .22 V2.2

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